

**MOLD COMPOUND CAP IN A  
FLIP CHIP MULTI-MATRIX ARRAY PACKAGE  
AND PROCESS OF MAKING SAME**

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**ABSTRACT OF THE DISCLOSURE**

A molding compound cap structure is disclosed. A process of forming the molding compound cap structure is also disclosed. A microelectronic package is also disclosed that uses the molding compound cap structure. A method of assembling a microelectronic package is also disclosed. A computing system is also 10 disclosed that includes the molding compound cap structure. The molding compound cap includes a configuration that exposes a portion of a microelectronic device.

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